

ABSTRACT OF THE DISCLOSURE

Embodiments of the present disclosure are directed to liners for glass vias and method for forming multi-layer liners for stress buffering in glass vias. In an embodiment, the method includes depositing a first sublayer over a surface of a substrate comprising a glass core and a via extending therethrough, in which the first sublayer comprises a compressive stress between about -500 MPa and about -1500 MPa. The method also includes depositing a second sublayer over the first sublayer inside the via, and a third sublayer over the second sublayer. The second sublayer comprises a Young's modulus between about 1 GPa and about 15 GPa, and the third sublayer comprises a stress between about -100 MPa and about -800 MPa compressive stress.

[Figure 3G]